	Type	L #	Hits	Search Text	DBs
1	BRS	L1	1582	257/786.ccls.	US-PGPUB; USPAT; USOCR
2	BRS	L2	1974	257/773.ccls.	US-PGPUB; USPAT; USOCR
3	BRS	L3	2554	257/778.ccls.	US-PGPUB; USPAT; USOCR
4	BRS	L4	1033	257/48.ccls.	US-PGPUB; USPAT; USOCR
5	BRS	L5	1864	257/737.ccls.	US-PGPUB; USPAT; USOCR
6	BRS	L6	356	257/786.ccls.	EPO; JPO; DERWENT; IBM_TDB
7	BRS	L7	449	257/773.ccls.	EPO; JPO; DERWENT; IBM_TDB
8	BRS	L8	335	257/48.ccls.	EPO; JPO; DERWENT; IBM_TDB
9	BRS	L9	30	((substrate or wafer or chip or die) and (electrode or pad or terminal) and (circuit or cell) and expose$3 and prob$3 and first and second and third).clm.	US-PGPUB

	Type	L #	Hits	Search Text	DBs
10	BRS	L10	47	((substrate or wafer or chip or die) and (electrode or pad or terminal) and (circuit or cell) and expose$3 and test and first and second and third).clm.	US-PGPUB